

This etch provides replacement buffer beams and solebars to convert the 9' W/B wooden underframe, Part No 2-330, into the equivalent metal chassis. The kit provides both square and angle ended bufferbeams.

To remove the components from the etch it is recommended that it is placed 1/2-etch lines down on a hard surface. The joining tabs are cut close to the waste material by pressing down firmly with a sharp curved scalpel blade (eg Swann Morton No 15). The freed components should then be turned over and the remainder of the tabs trimmed off close to the edges. Care must be taken with the sides of the solebar cosmetic infills.

The narrow flanges along the top and bottom edges of the solebars and buffer beams must be bent over at right-angles. It is recommended that this is achieved using Bend Tool Part No 2-350 and in accordance with the instructions supplied.

The 'V' hanger is formed down square and touch of Carr's 188 solder paste applied behind the bend points as reinforcement. The door stop is also folded down and again a touch of solder applied at the rear to secure it. It is bent to shape as in Fig 2. If the door stop isn't needed it is broken off.

An exploded view of the Chassis/Solebar/Buffer beam arrangement is shown, Fig 1.

The cosmetic solebar infills are glued in using a thin smear of Rapid Araldite at each end and at the centre. The ends of the infills must be aligned with the ends of the solebars and the square brake lever holes free from glue.

Place the basic chassis upside down on a flat surface and attach the solebars with Superglue or another smear of Araldite. If preferred a touch of glue will hold the parts in place while a tiny fillet of solder paste is run in. Care must be taken to set the solebars centrally to enable the buffer beams to fit properly. Thread a piece of 12 thou' wire through the 'V' hangers and the brake unit holes to check alignment.

The buffer beam channels clip over the ends of the solebars (see Fig 3) and can be fixed to the chassis buffer beam supports with a touch of solder paste (see Fig 4).

